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TO:	Examiner E. Lee GAU 2815	**PHONE #:**	(703) 305-5695
FROM:	Mark Zagorin	**DATE:**	January 30, 2003
SUBJECT:	Response to non-final Office action		
YOUR REF:	09/484,311	**OUR REF:**	1001-0087
FACSIMILE #:	(703) 308-7722	**PAGES:**	6 (including this transmittal)

MESSAGE

Please see attached

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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):	James John Casto et al.		
Title:	INTEGRATED CIRCUIT PACKAGE INCORPORATING PROGRAMMABLE ELEMENTS		
Application No.:	09/484,311	Filed:	January 18, 2000
Examiner:	E. Lee	Group Art Unit:	2815
Atty. Docket No.:	1001-0087		

January 30, 2003

COMMISSIONER FOR PATENTS
Washington, DC 20231

RESPONSE TO NON-FINAL OFFICE ACTION

This paper is responsive to a Non-Final Office Action dated October 30, 2002, having a shortened statutory period for response set to expire January 30, 2003.

REMARKS

Claims 2-12, 15-25, and 27 are pending in the application.

Claims 2-5, 10, 11, 17, 18, 22, and 23 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,369,437 B1 to MacPherson et al. MacPherson fails to teach a package comprising at least one one-time programmable element having a first and a second end separated by a programmable link. In the Office Action dated October 30, 2002, the Examiner states that "[t]he whole semiconductor device may be construed as a 'package.' For example, a semiconductor device such as a PAL, FPGA or PLD which contain fuses may be called a package or any substrate (i.e. circuit board) it is put on may be called a package." The Examiner relies on col. 1, line 46-col. 2, line 32 of MacPherson to support this statement. Applicants respectfully submit that the Examiner has misinterpreted the reference. MacPherson teaches at col. 1, lines 46-51 that PALs, FPGAs, and PLDs are fabricated and programmed after they are packaged units. However, MacPherson distinguishes between a device and a package and fails